## Discontinued Product

These parts are no longer in production The device should not be purchased for new design applications. Samples are no longer available.

Date of status change: May 7, 2013

## Recommended Substitutions:

For existing customer transition, and for new customers or new applications, refer to the All50.

NOTE: For detailed information on purchasing options, contact your local Allegro field applications engineer or sales representative.

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## HALL-EFFECT SWITCH FOR 2-WIRE APPLICATIONS

## Suffix 'UA' Pinning

(ultra-mini SIP)


Dwg. PH-003-7A

Pinning is shown viewed from branded side.

## ABSOLUTE MAXIMUM RATINGS

 at $T_{A}=+25^{\circ} \mathrm{C}$Supply Voltage, $\mathrm{V}_{\mathrm{CC}}$................ 26.5 V
Reverse Battery Voltage, $\mathrm{V}_{\text {RCC }} \ldots . . \mathbf{- 1 6}$ V
Magnetic Flux Density, B ..... Unlimited
Package Power Dissipation, $\mathrm{P}_{\mathrm{D}}$ See Graph
Junction Temperature, $\mathrm{T}_{\mathrm{J}} \ldots \ldots . .+\mathbf{1 7 0}^{\circ} \mathbf{C}$
Operating Temperature Range,
$\mathrm{T}_{\mathrm{A}}$........................ $\mathbf{- 4 0}{ }^{\circ} \mathrm{C}$ to $+\mathbf{8 5}{ }^{\circ} \mathrm{C}$
Storage Temperature Range,
$\mathrm{T}_{\mathrm{S}}$..................... $-\mathbf{6 5}^{\circ} \mathrm{C}$ to $+\mathbf{1 7 0}^{\circ} \mathrm{C}$

This Hall-effect switch is a monolithic integrated circuit designed to operate continuously over extended temperatures to $+85^{\circ} \mathrm{C}$. The unipolar switching characteristic makes this device ideal for use with a simple bar or rod magnet. The A3163ELT and A3163EUA are identical except for package.

Each device includes a voltage regulator for operation with supply voltages of 3.5 to 24 volts, reverse-battery protection, quadratic Hallvoltage generator for low offset, temperature compensation circuitry, small-signal amplifier, Schmitt trigger, and a constant-current opencollector output, wired internally for true 2 -wire operation. Noise radiation is limited by control of the output-current slew rate.

Two package styles provide a magnetically optimized package for most applications. Suffix 'LT' is a miniature SOT89/TO-243AA transistor package for surface-mount applications; suffix 'UA' is a three-lead ultra-mini SIP for through-hole mounting; it is also available with lead forming for surface-mount applications (suffix 'UA-TL').

## FEATURES and BENEFITS

- Internal Current Regulator for 2-Wire Operation
- Output Slew Rate Controlled
- 3.5 V to 24 V Operation ... Needs Only An Unregulated Supply
- Reverse Battery Protection
- Excellent Temperature Stability
- Activate with Small, Commercially Available Permanent Magnets
- Small Size
- Solid-State Reliability ... No Moving Parts
- Resistant to Physical Stress

Always order by complete part number, e.g., A3163ELT.

## FUNCTIONAL BLOCK DIAGRAM



Pinning is shown viewed from branded side.

## ELECTRICAL CHARACTERISTICS over operating voltage and temperature ranges.

| Characteristic | Symbol | Test Conditions | Limits |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Min. | Typ. | Max. | Units |
| Supply Voltage | $\mathrm{V}_{\mathrm{CC}}$ | Operating | 3.5 | - | 24 | V |
| Output Current | $\mathrm{I}_{\text {OUT(H) }}$ | $\mathrm{B}>\mathrm{B}_{\mathrm{OP}}$ | 12 | 14 | 17 | mA |
|  | $\mathrm{I}_{\text {OUT(L) }}$ | $B<B_{R P}$ | 5.0 | 5.6 | 6.9 | mA |
| Output Slew Rate | di/dt | $\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}$ | - | 7.0 | 20 | $\mathrm{mA} / \mu \mathrm{s}$ |
| Output Settling Time | $\mathrm{t}_{\text {sd }}$ | $\mathrm{C}_{\mathrm{L}}=20 \mathrm{pF}$ | - | - | 20 | $\mu \mathrm{s}$ |
| Reverse Battery Current | $\mathrm{I}_{\text {CCR }}$ | $\mathrm{V}_{\mathrm{RCC}}=-16 \mathrm{~V}$ | - | - | -15 | mA |

## MAGNETIC CHARACTERISTICS over operating supply voltage and temperature ranges.

| Characteristic | Limits |  |  |  |  |
| :--- | :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Typ. | Max. | Units |
|  |  | - | 98 | 160 | G |
|  | $\mathrm{B}_{\mathrm{RP}}$ | 30 | 79 | - | G |
|  | $\mathrm{B}_{\mathrm{hys}}$ | 5.0 | 19 | 40 | G |

NOTES: 1. Typical Data is at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ and $\mathrm{V}_{\mathrm{CC}}=12 \mathrm{~V}$ and is for design information only.
2. 1 gauss $(\mathrm{G})$ is exactly equal to 0.1 millitesla ( mT ).

## TYPICAL OPERATING CHARACTERISTICS




## ELEMENT LOCATIONS

( $\pm 0.005^{\prime \prime}[0.13 \mathrm{~mm}]$ die placement)
Suffix "LT"


Dwg. MH-008-8A

Suffix "UA"


## FUNCTIONAL DESCRIPTION

Operation. The output of these devices turns on when a magnetic field (south pole) perpendicular to the Hall element exceeds the operate point threshold ( $\mathrm{B}_{\mathrm{OP}}$ ). After turn on, the output will source current ( $\mathrm{I}_{\text {OUT(H) }}$ ) equal to the device operating current plus a current source. When the magnetic field is decreased (south pole) below the release point $\left(\mathrm{B}_{\mathrm{RP}}\right)$, the output will source current ( $\left.\mathrm{I}_{\mathrm{OUT}(\mathrm{L})}\right)$ equal to the Hall-effect device operating current with the current source turned off. The difference in the magnetic operate and release points is the hysteresis ( $\mathrm{B}_{\text {hys }}$ ) of the device. The hysteresis allows clean switching of the output even in the presence of external mechanical vibration or electrical noise.

Powering up in the absence of a magnetic field (less than $B_{O P}$ and higher than $B_{R P}$ ) will allow an indeterminate output state. The correct state is warranted after the first excursion beyond $\mathrm{B}_{\mathrm{OP}}$ or $\mathrm{B}_{\mathrm{RP}}$.


## APPLICATIONS INFORMATION

External Components. It is strongly recommended that an external bypass capacitor be connected (in close proximity to the Hall element) between the supply and ground of the device.
Power Derating. Due to the internal device power dissipation, the junction temperature $\left(\mathrm{T}_{\mathrm{J}}\right)$ will be higher than the ambient temperature $\left(\mathrm{T}_{\mathrm{A}}\right)$. To ensure that the absolute maximum junction temperature is not exceeded, the following equations should be applied:

$$
\mathrm{T}_{\mathrm{J}}=\mathrm{T}_{\mathrm{A}}+\left(\mathrm{P}_{\mathrm{D}} \times \mathrm{R}_{\theta \mathrm{\theta} A}\right)
$$

where $P_{D}$ is the maximum supply power

$$
\mathrm{I}_{\mathrm{OUT}(\mathrm{H})} \times \mathrm{V}_{\mathrm{CC}}
$$

and $R_{\theta A A}$ is the package thermal resistance. The specified limit for $\mathrm{I}_{\text {OUT(H) }}$ should be used to ensure a margin of safety.

Magnets. The simplest form of magnet that will operate this device is a ring magnet. Other methods of operation, such as linear magnets, are possible.


## TYPICAL APPLICATION

Extensive applications information for Hall-effect devices is available in:

- Hall-Effect IC Applications Guide, Application Note 27701;
- Hall-Effect Devices: Soldering, Gluing, Potting, Encapsulating, and Lead Forming, Application Note 27703.1;
- Soldering of Through-Hole Hall-Sensor Dervices, Application Note 27703;
- Soldering of Surface-Mount Hall-Sensor Devices, Application Note 27703.2; and
- Two-Wire Hall-Effect Sensors, Application Note 27704.

All are provided in Allegro Electronic Data Book, AMS-702 or at
www.allegromicro.com

## CRITERIA FOR DEVICE QUALIFICATION

All Allegro devices are subjected to stringent qualification requirements prior to being released to production. To become qualified, except for the destructive ESD tests, no failures are permitted.

| Qualification Test | Test Method and Test Conditions | Test Length | Samples | Comments |
| :---: | :---: | :---: | :---: | :---: |
| Biased Humidity (HAST) | $\mathrm{T}_{\mathrm{A}}=130^{\circ} \mathrm{C}, \mathrm{RH}=85 \%$ | 50 hrs | 77 | $\mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\text {OUT }}=5 \mathrm{~V}$ |
| High-Temperature Operating Life (HTOL) | $\begin{aligned} & \text { JESD22-A108, } \\ & T_{A}=150^{\circ} \mathrm{C}, \mathrm{~T}_{J} \leq 165^{\circ} \mathrm{C} \end{aligned}$ | 408 hrs | 77 | $\begin{aligned} & V_{\text {cC }}=24 \mathrm{~V}, \\ & \mathrm{~V}_{\text {out }}=20 \mathrm{~V} \end{aligned}$ |
| Accelerated HTOL | $\mathrm{T}_{\mathrm{A}}=175^{\circ} \mathrm{C}, \mathrm{T}_{\mathrm{J}}=190^{\circ} \mathrm{C}$ | 504 hrs | 77 | $\begin{aligned} & V_{\text {cC }}=24 \mathrm{~V}, \\ & \mathrm{~V}_{\text {out }}=20 \mathrm{~V} \end{aligned}$ |
| Autoclave, Unbiased | JESD22-A102, Condition C, $\mathrm{T}_{\mathrm{A}}=121^{\circ} \mathrm{C}, 15 \mathrm{psig}$ | 96 hrs | 77 |  |
| High-Temperature (Bake) Storage Life | $\begin{aligned} & \text { MIL-STD-883, Method 1008, } \\ & \mathrm{T}_{\mathrm{A}}=170^{\circ} \mathrm{C} \end{aligned}$ | 1000 hrs | 77 |  |
| Temperature Cycle | MIL-STD-883, Method 1010, $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ | 500 cycles | 77 |  |
| Latch-Up | - | Pre/Post <br> Reading | 6 |  |
| Electro-Thermally Induced Gate Leakage | - | Pre/Post Reading | 6 |  |
| ESD, <br> Human Body Model | CDF-AEC-Q100-002 | Pre/Post <br> Reading | $3 \text { per }$ test | Test to failure, All leads $>4 \mathrm{kV}$ |
| ESD, <br> Machine Model | JESD22-A115 | Pre/Post Reading | $3 \text { per }$ test | Test to failure, <br> All leads $>700 \mathrm{~V}$ |
| Electrical Distributions | Per Specification | - | 30 |  |

# PACKAGE DESIGNATOR 'LT' <br> (SOT89/TO-243AA) 

Dimensions in Inches
(for reference only)


Dwg. MA-009-3A in


Dwg. MA-009-3A mm
Dimensions in Millimeters
(controlling dimensions)


Pads 1, 2, 3, and A - Standard SOT89 Layout
Pads 1, 2, 3, and B - Low-Stress Version
Pads 1, 2, and 3 only - Lowest Stress, But Not Self Aligning
Dwg. MA-012-3 in


Pads 1, 2, 3, and A - Standard SOT89 Layout
Pads 1, 2, 3, and B-Low-Stress Version
Pads 1, 2, and 3 only - Lowest Stress, But Not Self Aligning

NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.
2. Supplied in bulk pack ( 500 pieces per bag) or add "TR" to part number for tape and reel.
3. Only low-temperature $\left(\leq 240^{\circ} \mathrm{C}\right)$ reflow-soldering techniques are recommended for SOT89 devices.

## PACKAGE DESIGNATOR ‘UA’

Dimensions in Inches (controlling dimensions)


NOTES: 1. Tolerances on package height and width represent allowable mold offsets. Dimensions given are measured at the widest point (parting line).
2. Exact body and lead configuration at vendor's option within limits shown.
3. Height does not include mold gate flash.
4. Recommended minimum PWB hole diameter to clear transition area is $0.035^{\prime \prime}(0.89 \mathrm{~mm})$.
5. Where no tolerance is specified, dimension is nominal.
6. Supplied in bulk pack ( 500 pieces per bag).

## Dimensions in Millimeters

(for reference only)


Dwg. MH-014E mm


NOTE: Lead-form dimensions are the nominals produced on the forming equipment. No dimensional tolerance is implied or guaranteed for bulk packaging ( 500 pieces per bag).

The products described herein are manufactured under one or more of the following U.S. patents: 5,045,920; 5,264,783; 5,442,283; 5,389,889; 5,581,179; 5,517,112; 5,619,137; 5,621,319; 5,650,719; 5,686,894; 5,694,038; 5,729,130; 5,917,320; and other patents pending.

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